

**Michael W. Smith**  
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Monument, Colorado 80132  
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**Employment Objectives:** A full time position with full benefits and the opportunity to demonstrate my skills and knowledge. I will use my skill and knowledge to positively impact the Company's profit.

**Qualifications:** A confident forthright attitude due to my personal background as well as past successes. I am a hard-working, self-starting individual who works well in a team environment, responsible in both supervisory and individual contributor roles. I also possess an ability and willingness to learn new techniques and/or ideas.

**Education:** 2010-12 Graduated from Devry University  
2006 Graduated from the I.C. Institute  
1991-94 Western State College.  
1992 Summer courses at U.C.C.S.  
1988-90 Pikes Peak Community College.

**Experience:**

**Aug 2009 – Apr 2019. Samtec Microelectronics.** Process Engineering Technician for the Saw/Sort/Inspect Area. Responsible for supporting Production associates. Responsibilities included: disposition of quality issues, identifying, testing and implementing process improvements. Worked with Product Engineers and customers to create new processes or improve existing processes. Also had supporting duties for other areas of the packaging process (Fiber Attach and Final packaging).

**Jan 2006 – Dec 2008. Atmel Corporation.** Equipment Engineering Technician for the Thin Films Area. Responsible for repair and routine maintenance of equipment used in the production of semi-conductors. Supported Process and Equipment Engineering projects/experiments to reduce tool downtime and product scrap while improving product throughput and yield. Supported Company projects to reduce wafer costs and improve line yield.

**May 2005 – Jan 2006. Atmel Corporation.** Production Operator in the Diffusion Area. Certified to run the FSI, Oxide, LPCVD and POCL processes, as well as JT Probe.

**January 2004 – April 2005. Atmel Corporation.** Process Engineering Technician for the Diffusion Group. Responsible for supporting the Wafer Fab, handling wafer dispositions, diagnosing/solving tool issues, and supporting Engineering projects.

**July 2002- January 2004. Atmel Corporation.** Production Operator in the Diffusion area. Certified to run the FSI, Oxide, LPCVD, Alloy and POCL processes, as well as JT Probe. I am also a member of the Scrap Prevention Team for the Diffusion area.

**July 1997- July 2000. LSI Logic Inc.** Process Engineering Technician for the Thin Films Group. Responsible for supporting the Wafer Fab, handling wafer dispositions, diagnosing/solving tool issues, and supporting Engineering projects. Supported efforts to reduce D(0) for several technologies, increase Line Yields, as well as other Company Goals described in "Achieve" through SPC as well as process improvements. Was promoted to Technician Level 2 in May of 1998 due to hard work and good judgement.

**January 1995-July 1997. Symbios Logic.** Fabrication Operator held certifications on multiple machines in several different areas. Held certifications on the implanters in the Diffusion area. All CVD, HDP, and sputtering deposition tools in the Thin Films area. I also held certifications on the Inspex, KLA 21xx, and Ultrapointe machines used in defect density measurements.